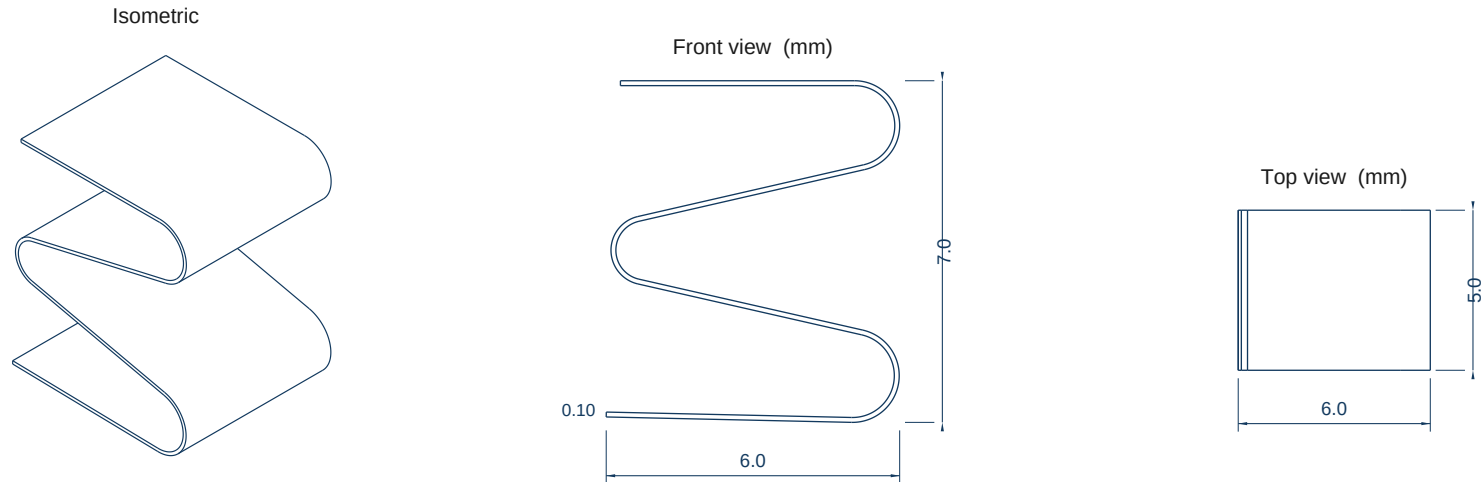




Type 3-02 B302-50060070

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.10 mm
Width	5.0 mm +/- 0.2
Length	6.0 mm +/- 0.2
Height	7.0 mm +/- 0.2
Form	S-form: top plate, 3 folds, 2 diagonal webs, base plate
Folds	R0.869/167 deg R0.657/154 deg R0.905/168 deg CL
Webs	4.74 mm and 4.69 mm
Plates	top 4.79 mm, base 5.02 mm
Base hole	none - no hole on the drawing or render
Developed length	26.20 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	13.101 mm ³ 109.5 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	B302-50060070G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 6.0x5.0x7.0mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-3-02.html
File format	STEP AP214